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# Environmental testing—Part 2-69: Tests—Test Te: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method

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# Contents

Page

Introduction ........ 1

1 Scope ........ 1

2 Normative references ........ 1

3 Terms and definitions ........ 2

4 General description of the method ........ 2

5 Description of the test apparatus ........ 3

6 Preconditioning ........ 3
6.1 Preparation of specimens ........ 3
6.2 Ageing ........ 3

7 Materials ........ 4
7.1 Solder ........ 4
7.2 Flux ........ 4

8 Procedures ........ 5
8.1 Test temperature ........ 5
8.2 Solder bath wetting balance procedure ........ 5
8.3 Solder globule wetting balance procedure ........ 7

9 Presentation of results ........ 11
9.1 Form of force versus time trace ........ 11
9.2 Test requirements ........ 12

10 Information to be given in the relevant specification ........ 13

Annex A (normative) Equipment specification ........ 14

Annex B (informative) Use of the wetting balance for SMD solderability testing ........ 16

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